

ABSTRACT

ELECTRICAL INTERCONNECTION FOR HIGH-FREQUENCY DEVICES

5 Wire bonds connect current-carrying edges of high-frequency planar conductors to
other electrical devices. In one embodiment, planar transmission lines are interconnected
using two wire bonds. One bond wire extends from an edge of a first center conductor to a
corresponding edge of a second center conductor, and a second bond wire extends from
the other edge of the first center conductor to the other edge of the second center
10 conductor. Embodiments include center conductors at different heights and having
different widths, and different electrical devices, such as semiconductor integrated circuits.
In a particular embodiment, ball bonding is used. In some embodiments, a tack bond is
included after a ball bond to allow closer attachment of the bond wire to the edge of the
conductor.